









# PRODUCT DATASHEET



- ► EMC 2-PIN SMD
- ➤ 2016 0.52t Series
- ► True Green (525nm)

N0G20S39





# **2016 0.52t Series**





#### **FEATURES:**

Package: TOP View EMC White SMT Package

Forward Current: 40mA Forward Voltage (typ.): 3.0V Luminous Flux (typ.): 10lm@40mA

Colour: True Green Wavelength: 520-535nm Viewing angle: 120°

**Materials:** Die: InGaN

> Resin: Silicon (Water Clear) L/T Finish: Ag plated

Operating Temperature: -40~+85°C Storage Temperature: -40~+105°C

**Grouping parameters:** 

Forward Voltage

Luminous Flux

**Dominant Wavelength** Soldering methods: Reflow

NSL Level: 3 according to J-STD020

Packing: 8mm tape with Max.5000/reel, ø165mm (6.5")

### **APPLICATIONS:**

- **Decorative Lighting**
- Portable Lighting
- **Outdoor Lighting**
- **Commercial Lighting**
- **Architectural Lighting**



### **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I <sub>F</sub>	50	mA
Pulse Forward Current (width≤100μS; duty≤1/10)	I <sub>FP</sub>	75	mA
Power Dissipation	P <sub>D</sub>	170	mW
Reverse Voltage	VR	5	V
Reverse Current @5V	I <sub>R</sub>	10	μΑ
Junction Temperature	Tj	110	°C
Electrostatic Discharge (HBM: MIL-STD-883 C 2)	ESD	1000	V
Operating Temperature	T <sub>OPR</sub>	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+105	°C
Soldering Temperature (10s)	T <sub>SLD</sub>	260	°C

# Electrical & Optical Characteristics (Ta=25°C)

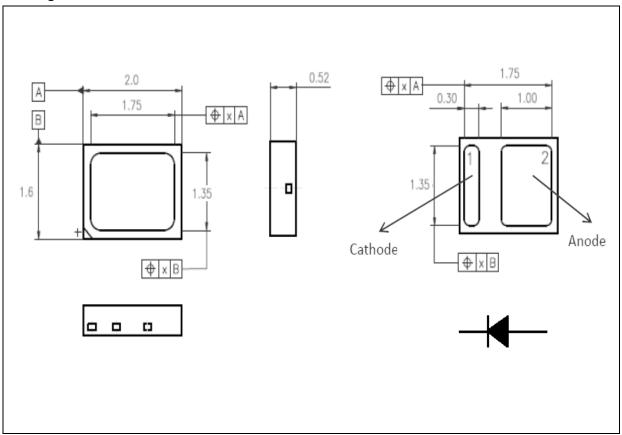
Parameter	Symbol	Values			Unit	Test
	Зуппоп	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	$V_{F}$	2.6	3.0	3.4	V	I <sub>F</sub> =40mA
Luminous Flux	Ф۷	8	10		lm	I <sub>F</sub> =40mA
Dominant Wavelength	$\lambda_{D}$	520		535	nm	I <sub>F</sub> =40mA
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =40mA

<sup>1.</sup> Luminous flux ( $\Phi_V$ ) ±7%, Forward Voltage ( $V_F$ ) ±0.1V



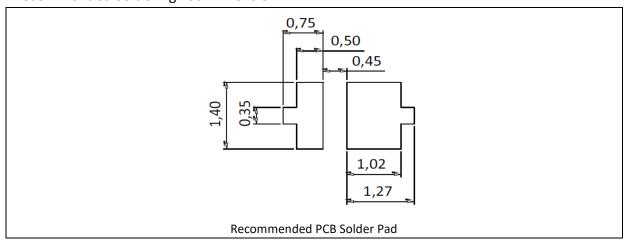
### **OUTLINE DIMENSION:**

### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

### Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



### **BINNING GROUPS:**

# Forward Voltage Classifications (I<sub>F</sub> = 40mA):

Code	Min.	Max.	Unit
V2628	2.6	2.8	
V2830	2.8	3.0	V
V3032	3.0	3.2	V
V3234	3.2	3.4	

### Luminous Flux Classifications ( $I_F = 40 \text{mA}$ ):

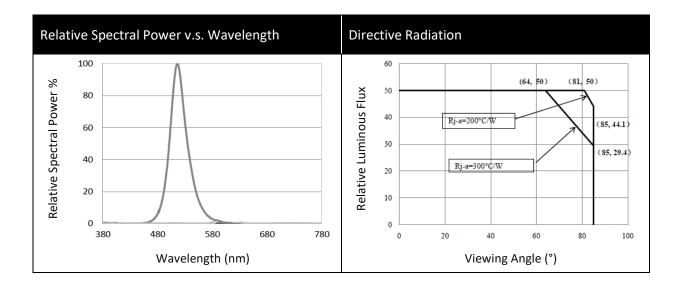
Code	Min.	Max.	Unit
AE	8	10	
AF	10	14	lm
AG	14	18	

# Dominant Wavelength Classifications (I<sub>F</sub> = 40mA):

Code	Min.	Max.	Unit
G1	520	525	
G2	525	530	nm
G3	530	535	



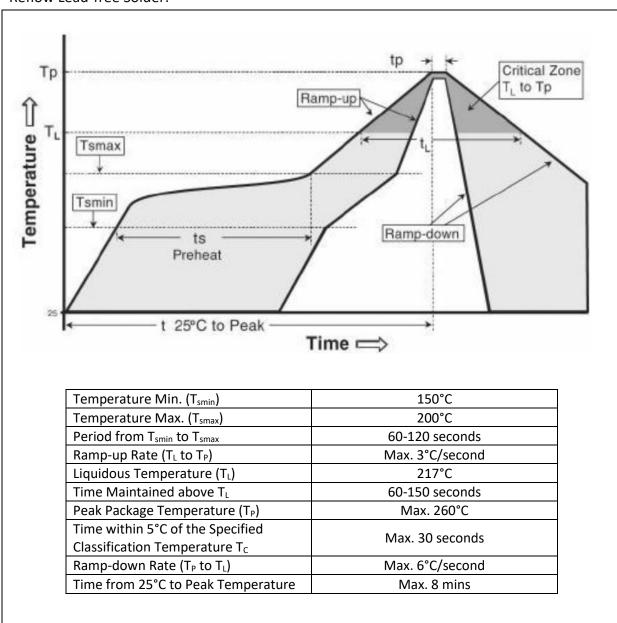
### **ELECTRO-OPTICAL CHARACTERISTICS:**





#### **RECOMMENDED SOLDERING PROFILE:**

#### Reflow Lead-free Solder:



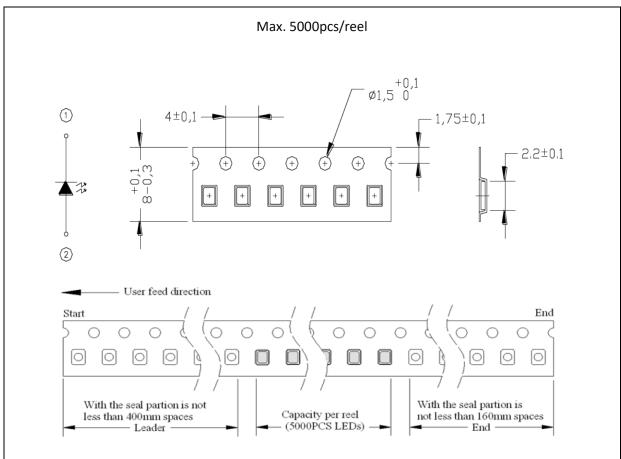
#### Note:

- 1. Maximum reflow soldering: 2 times within 24 hours.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.
- 3. Recommended soldering temperature: 230°C. The maximum soldering temperature should be limited to 260°C for max. 10seconds.

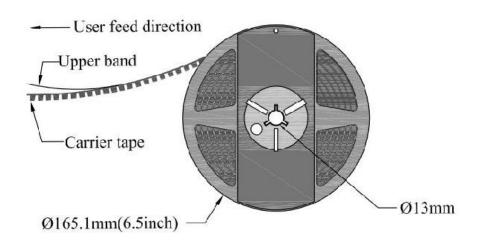


### **PACKING SPECIFICATION:**

#### Reel Dimension:



- 1. Cumulative Tolerance : Cumulative Tolerance/10 pitches to be ±0.2mm
- 2. Adhesion Strength of Cover Tape Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape.





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

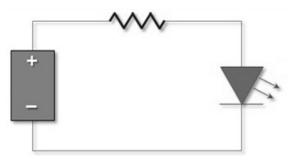
### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	14/12/2016	Datasheet set-up.
A1.1	10/05/2017	Revise spectrum graphic.
A1.2	21/11/2022	Update bin tables.